Dual General Purpose Transistor

The MBT3906DW1 device is a spin-off of our popular SOT-23/SOT-323 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-363 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

Features

- h_{FE}, 100-300
- Low $V_{CE(sat)}$, $\leq 0.4 \text{ V}$
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Available in 8 mm, 7-inch/3,000 Unit Tape and Reel
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--------------------------------|------------------|---------------------------|------|
| Collector - Emitter Voltage | V _{CEO} | -40 | Vdc |
| Collector - Base Voltage | V _{CBO} | -40 | Vdc |
| Emitter – Base Voltage | V _{EBO} | -5.0 | Vdc |
| Collector Current - Continuous | Ic | -200 | mAdc |
| Electrostatic Discharge | ESD | HBM Class 2 MM Class B | |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|-----------------------------------|-------------|------|
| Total Package Dissipation (Note 1) T _A = 25°C | P _D | 150 | mW |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 833 | °C/W |
| Junction and Storage Temperature Range | T _J , T _{stg} | -55 to +150 | °C |

Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.



ON Semiconductor®

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MARKING DIAGRAM



SOT-363/SC-88 CASE 419B STYLE 1



XX = Device Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

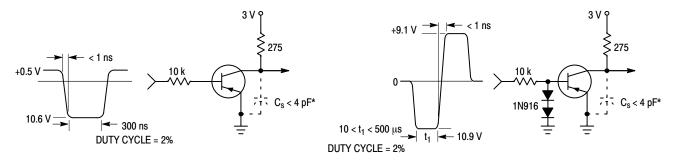
ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C unless otherwise noted)

| Characteristic | | Symbol | Min | Max | Unit | |
|---|---|----------------------|-----------------------------|--------------------|--------------------|--|
| OFF CHARACT | ERISTICS | 1 | | JI | | |
| Collector - Emitter | r Breakdown Voltage (Note 2) | V _{(BR)CEO} | -40 | _ | Vdc | |
| Collector - Base E | Breakdown Voltage | V _{(BR)CBO} | -40 | - | Vdc | |
| Emitter - Base Bre | eakdown Voltage | V _{(BR)EBO} | -5.0 | _ | Vdc | |
| Base Cutoff Curre | ent | I _{BL} | (BTI)EBS | | | |
| Collector Cutoff C | Current | I _{CEX} | | | | |
| ON CHARACTE | RISTICS (Note 2) | <u> </u> | | ı | | |
| $(I_C = -1.0 \text{ mAdd})$ $(I_C = -10 \text{ mAdd})$ $(I_C = -50 \text{ mAdd})$ | c, $V_{CE} = -1.0 \text{ Vdc}$) c, $V_{CE} = -1.0 \text{ Vdc}$) c, $V_{CE} = -1.0 \text{ Vdc}$) c, $V_{CE} = -1.0 \text{ Vdc}$) dc, $V_{CE} = -1.0 \text{ Vdc}$) | h _{FE} | 60 80 100 60 30 | - 300 - - | - | |
| $(I_C = -10 \text{ mAdd})$ | r Saturation Voltage c, $I_B = -1.0 \text{ mAdc}$) c, $I_B = -5.0 \text{ mAdc}$) | V _{CE(sat)} | - - | -0.25 -0.4 | Vdc | |
| | turation Voltage c, $I_B = -1.0 \text{ mAdc}$ c, $I_B = -5.0 \text{ mAdc}$ | V _{BE(sat)} | -0.65 - | -0.85 -0.95 | Vdc | |
| SMALL-SIGNA | L CHARACTERISTICS | | | | | |
| Current - Gain - E | Bandwidth Product | f⊤ | 250 | - | MHz | |
| Output Capacitan | ce | C _{obo} | - | pF | | |
| Input Capacitance | 9 | C _{ibo} | - | pF | | |
| Input Impedance (V _{CE} = -10 Vdd | c, I _C = -1.0 mAdc, f = 1.0 kHz) | h _{ie} | 2.0 | 12 | kΩ | |
| Voltage Feedback (V _{CE} = -10 Vdd | c Ratio c, I _C = -1.0 mAdc, f = 1.0 kHz) | h _{re} | 0.1 | 10 | X 10 ⁻⁴ | |
| Small – Signal Cur (V _{CE} = -10 Vdd | rrent Gain c, I _C = -1.0 mAdc, f = 1.0 kHz) | h _{fe} | 100 | 400 | _ | |
| Output Admittanc (V _{CE} = -10 Vdc | e c, I _C = -1.0 mAdc, f = 1.0 kHz) | h _{oe} | 3.0 | 60 | μmhos | |
| Noise Figure (V _{CE} = -5.0 Vd | c, $I_C = -100 \mu Adc$, $R_S = 1.0 k \Omega$, $f = 1.0 kHz$) | NF | _ | 4.0 | dB | |
| SWITCHING CH | IARACTERISTICS | · | | | | |
| Delay Time | $(V_{CC} = -3.0 \text{ Vdc}, V_{BE} = 0.5 \text{ Vdc})$ | t _d | = | 35 | | |
| Rise Time | $(I_C = -10 \text{ mAdc}, I_{B1} = -1.0 \text{ mAdc})$ | t _r | - | 35 | ns | |
| Storage Time | $(V_{CC} = -3.0 \text{ Vdc}, I_{C} = -10 \text{ mAdc})$ | t _s | = | 225 | | |
| Fall Time | $(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$ | t _f | _ | 75 | ns | |



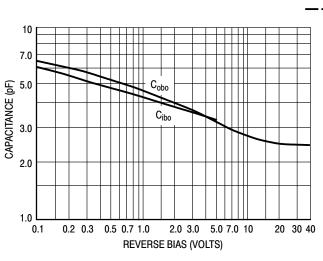
* Total shunt capacitance of test jig and connectors

Figure 1. Delay and Rise Time Equivalent Test Circuit

Figure 2. Storage and Fall Time Equivalent Test Circuit

TYPICAL TRANSIENT CHARACTERISTICS

• T_J = 25°C



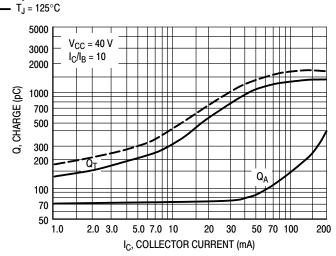
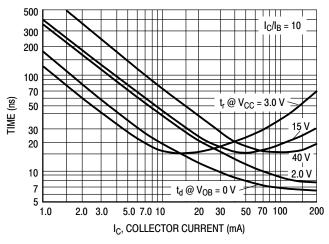


Figure 3. Capacitance

Figure 4. Charge Data



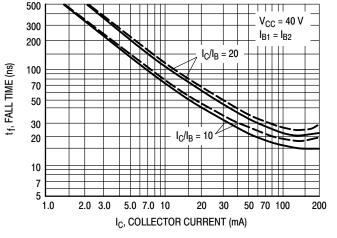
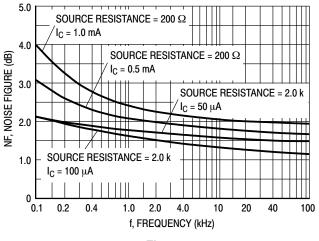


Figure 5. Turn - On Time

Figure 6. Fall Time

TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth = 1.0 \text{ Hz})$



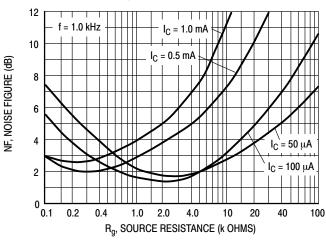
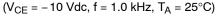
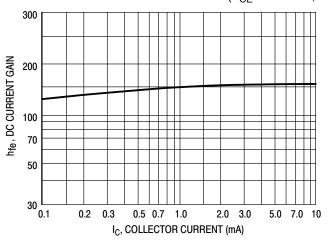


Figure 7.

Figure 8.

h PARAMETERS





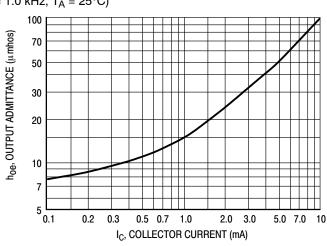
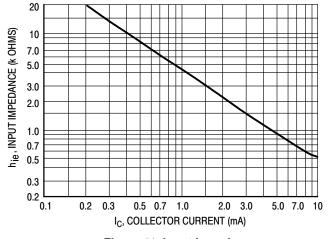


Figure 9. Current Gain

Figure 10. Output Admittance



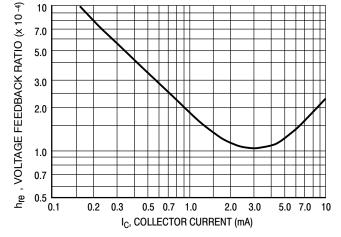


Figure 11. Input Impedance

Figure 12. Voltage Feedback Ratio

TYPICAL STATIC CHARACTERISTICS

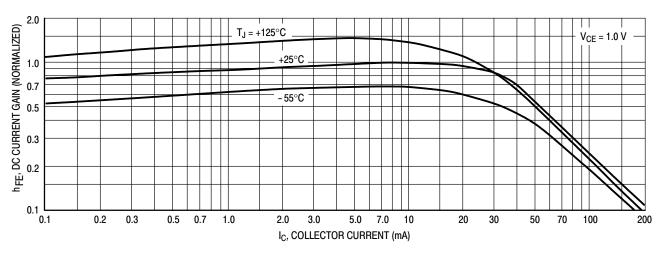


Figure 13. DC Current Gain

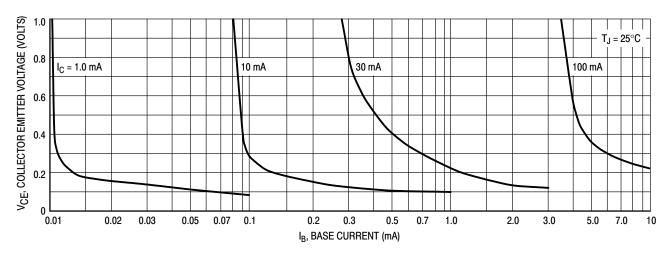


Figure 14. Collector Saturation Region

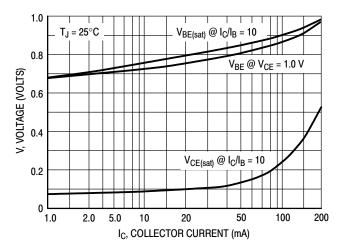


Figure 15. "ON" Voltages

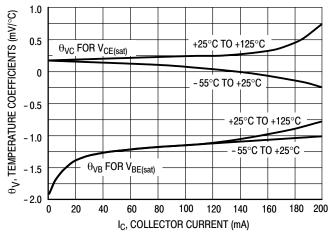


Figure 16. Temperature Coefficients

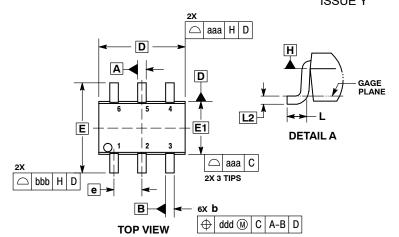
DEVICE ORDERING INFORMATION

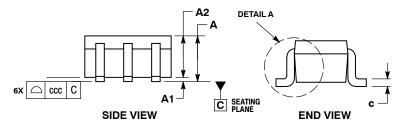
| Device | Marking | Pin Out | Package | Shipping [†] |
|----------------|---------|------------------|----------------------|-----------------------|
| MBT3906DW1T1G | A2 | 6 5 4 1 2 3 | SOT-363 (Pb-Free) | 3000 / Tape & Reel |
| SMBT3906DW1T1G | A2 | 6 5 4 | SOT-363 (Pb-Free) | 3000 / Tape & Reel |
| SMBT3906DW3T1G | АЗ | 5 5 4 D 1 2 3 | SOT-363 (Pb-Free) | 3000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**

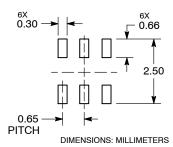




- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRU-
- SIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF
- THE PLASTIC BODY AND DATUM H.
 DATUMS A AND B ARE DETERMINED AT DATUM H.
- DATUMS A AND B ARE DETERMINED AT DATUM H.
 DIMENSIONS b AND 6 APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
 DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
 ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN
 EXCESS OF DIMENSION b AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

| | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|-----------|-------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | | | 1.10 | | | 0.043 |
| A1 | 0.00 | | 0.10 | 0.000 | | 0.004 |
| A2 | 0.70 | 0.90 | 1.00 | 0.027 | 0.035 | 0.039 |
| b | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| С | 0.08 | 0.15 | 0.22 | 0.003 | 0.006 | 0.009 |
| D | 1.80 | 2.00 | 2.20 | 0.070 | 0.078 | 0.086 |
| E | 2.00 | 2.10 | 2.20 | 0.078 | 0.082 | 0.086 |
| E1 | 1.15 | 1.25 | 1.35 | 0.045 | 0.049 | 0.053 |
| е | 0.65 BSC | | | 0.026 BSC | | |
| L | 0.26 | 0.36 | 0.46 | 0.010 | 0.014 | 0.018 |
| L2 | 0.15 BSC | | | 0.006 BSC | | |
| aaa | 0.15 | | | 0.006 | | |
| bbb | 0.30 | | | 0.012 | | |
| ccc | 0.10 | | | 0.004 | | |
| ddd | 0.10 | | | | 0.004 | |

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2

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